Operating Temperature	T_{opr}	-40~+110	
Junction Temperature	T_j	125	
Storage Temperature	T_{stg}	-55~+125	
Soldering Temperature	T_{sol}	260	

: 100μs pulse, 100Hz frequency

: AC for 1minute, R.H.=40~60%

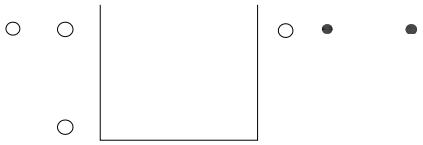
(Temperature=25°C)

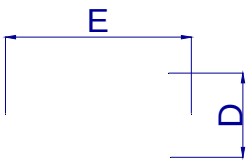
Input	Forward Voltage	V_F	I_F=10mA	-	1.2	1.5	V
	Reverse Current	I_R	V_R=6V	-	-	1	μA
Output	Open Circuit Voltage	V_{OC}	I_F=10mA I_O=0mA	7	-	-	V
	Short Circuit Current	I_{SC}	I_F=10mA V_O=0V	10	-	-	μA
Transfer Characteristics	Isolation resistance	R_{IO}	DC500V 40~60%R.H.	10^{12}	-	-	Ω
	Response Time	t_{on}	I_F=10mA	-	100	-	μs
		t_{off}		-	50	-	μs

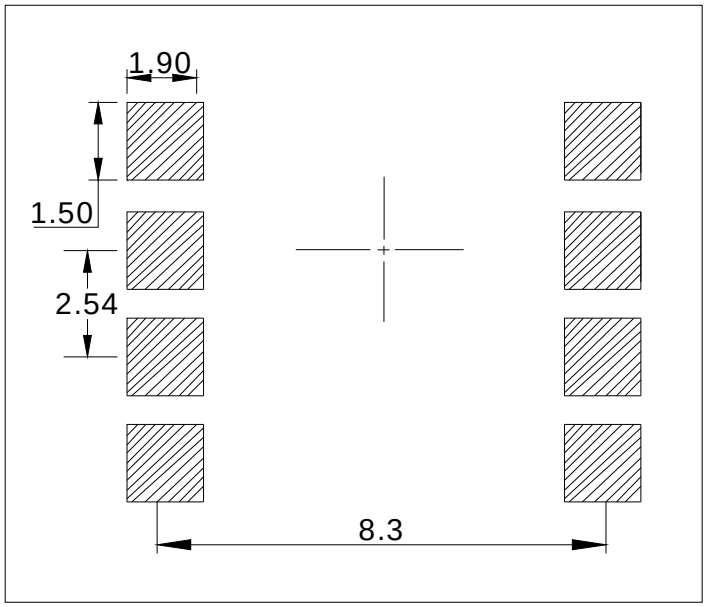
TEL

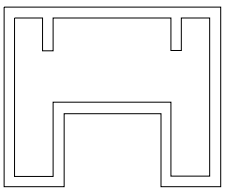
Max. Allowable LED Forward Current vs. Ambient Temperature

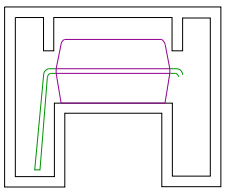
Forward Current vs. Forward Voltage

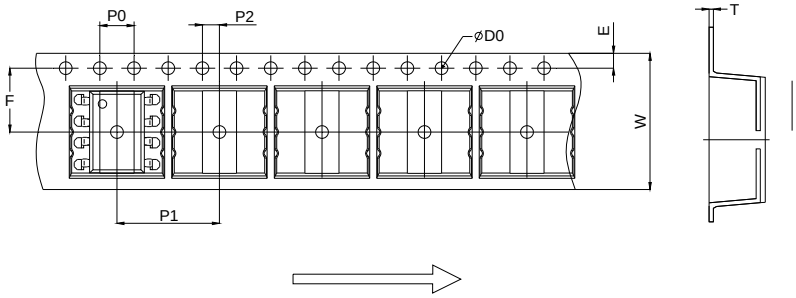



E
D

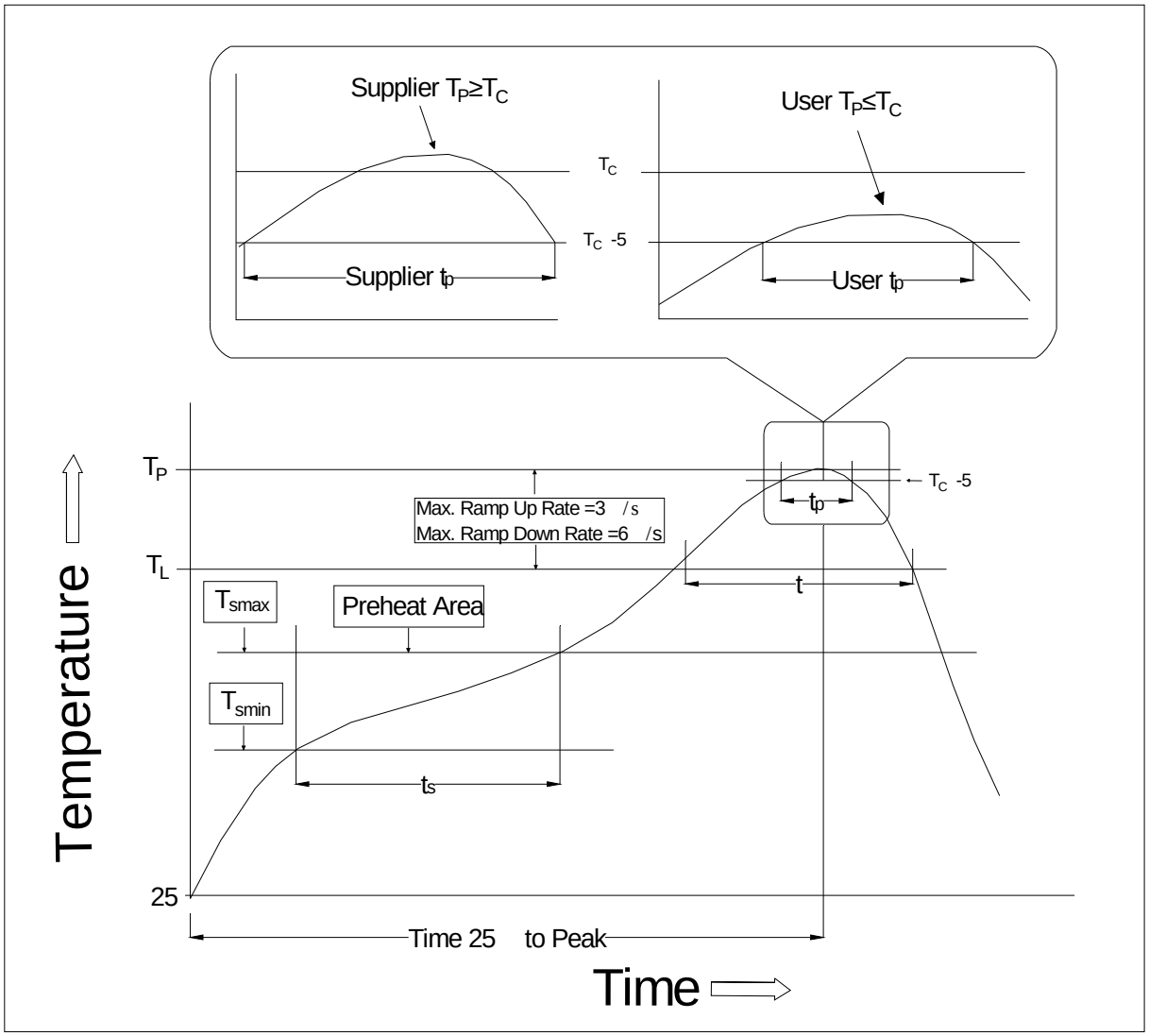

1.90
1.50
2.54
8.3



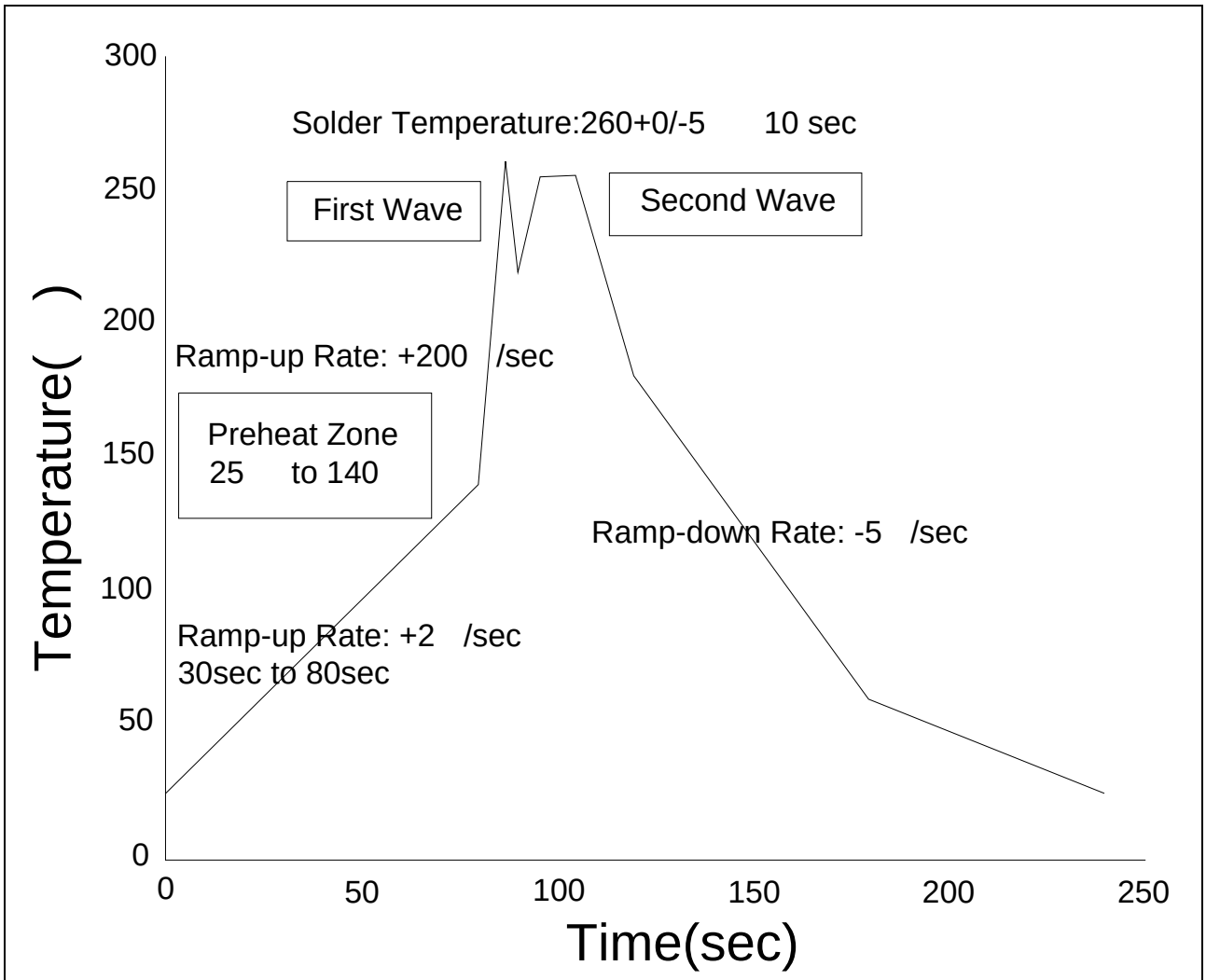




Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.90	16.00	16.20	0.626	0.630	0.638



Temperature Min. (Tsmin)	100	150
Temperature Max. (Tsmax)	150	200
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3 /second max.	3 /second max.
Liquidus Temperature (TL)	183	217
Time (tL) Maintained Above (TL)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5
Time (tP) within 5 of 260	10 seconds	10 seconds
Ramp-down Rate (TP to TL)	3-6 /second	3-6 /second
Time 25 to Peak Temperature	6 minutes max.	8 minutes max.



Soldering Temperature	360 ± 5
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1

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